MOSFET – Power, N-Channel, SUPERFET[®] III 800 V, 360 mΩ, 13 A

NTP360N80S3Z

Description

800 V SUPERFET III MOSFET is ON Semiconductor's high performance MOSFET family offering 800 V breakdown voltage.

New 800 V SUPERFET III MOSFET which is optimized for primary switch of flyback converter, enables lower switching losses and case temperature without sacrificing EMI performance thanks to its optimized design. In addition, internal Zener Diode significantly improves ESD capability.

This new family of 800 V SUPERFET III MOSFET enables to make more efficient, compact, cooler and more robust applications because of its remarkable performance in switching power applications such as Laptop adapter, Audio, Lighting, ATX power and industrial power supplies.

Features

- Typ. $R_{DS(on)} = 300 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Qg = 25.3 nC)
- Low Stored Energy in Output Capacitance (Eoss = 2.72 μJ @ 400 V)
- 100% Avalanche Tested
- ESD Improved Capability with Zener Diode
- RoHS Compliant

Applications

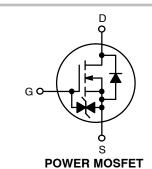
- Adapters / Chargers
- LED Lighting
- AUX Power
- Audio
- Industrial Power



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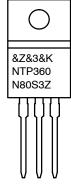
V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
800 V	360 m Ω	13 A



G

S TO-220 CASE 340AT

MARKING DIAGRAM



&Z = Assembly Plant Code &3 = Data Code (Year & Week)

&K = Lot

NTP360N80S3Z = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_J = 25^{\circ}C$, unless otherwise noted)

Symbol	Parameter		Value	Unit V	
V_{DSS}	Drain-to-Source Voltage	age			
V_{GS}	Gate-to-Source Voltage	DC	±20	V	
		AC (f > 1 Hz)	±30	1	
I _D	Drain Current	Continuous (T _C = 25°C)	13	Α	
		Continuous (T _C = 100°C)	8.2	1	
I _{DM}	Drain Current	Pulsed (Note 1)	32.5	Α	
E _{AS}	Single Pulsed Avalanche Energy (Note	ne Current (Note 2)		mJ	
I _{AS}	Avalanche Current (Note 2)			А	
E _{AR}	Repetitive Avalanche Energy (Note 1)			mJ	
dv/dt	MOSFET dv/dt	100	V/ns		
	Peak Diode Recovery dv/dt (Note 3)		10	1	
P_{D}	Power Dissipation	(T _C = 25°C)	96	W	
		Derate Above 25°C	0.768	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Ra	nge .	-55 to +150	°C	
T_L	Lead Temperature Soldering Reflow for (1/8" from Case for 10 seconds)	Lead Temperature Soldering Reflow for Soldering Purposes (1/8" from Case for 10 seconds)		°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. Repetitive rating: pulse–width limited by maximum junction temperature.
2. $I_{AS} = 2.0 \text{ A}$, $R_{G} = 25 \Omega$, starting $T_{J} = 25^{\circ}\text{C}$.
3. $I_{SD} \leq 3.25 \text{ A}$, $di/dt \leq 200 \text{ A}/\mu\text{s}$, $V_{DD} \leq 400 \text{ V}$, starting $T_{J} = 25^{\circ}\text{C}$.

THERMAL RESISTANCE RATINGS

Symbol	Parameter	Value	Unit
$R_{ hetaJC}$	Junction-to-Case - Steady State	1.3	°C/W
$R_{ heta JA}$	Junction-to-Ambient - Steady State	62.5	

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NTP360N80S3Z	NTP360N80S3Z	TO-220	Tube	N/A	N/A	50 Units

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	TERISTICS			•	•	•
BV _{DSS}	Drain-to-Source Breakdown Voltage	$V_{GS} = 0 \text{ V, } I_D = 1 \text{ mA, } T_J = 25^{\circ}\text{C}$	800			V
		V _{GS} = 0 V, I _D = 1 mA, T _J = 150°C	900			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 1 mA, Referenced to 25°C		1.1		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 800 V, V _{GS} = 0 V			1	μΑ
		V _{DS} = 640 V, T _C = 125°C		0.8		1
I _{GSS}	Gate-to-Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			1	μΑ
ON CHARACTI	ERISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 0.3 \text{ mA}$	2.2		3.8	V
R _{DS(on)}	Static Drain-to-Source On Resistance	V _{GS} = 10 V, I _D = 6.5 A		300	360	mΩ
9FS	Forward Transconductance	V _{DS} = 20 V, I _D = 6.5 A		13.8		S
DYNAMIC CHA	RACTERISTICS			•	•	•
C _{iss}	Input Capacitance	V _{DS} = 400 V, V _{GS} = 0 V, f = 250 kHz		1143		pF
C _{oss}	Output Capacitance			18.1		pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		236.4		pF
C _{oss(er.)}	Energy Related Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		34		pF
Q _{g(tot)}	Total Gate Charge at 10 V	V _{DS} = 400 V, I _D = 6.5 A, V _{GS} = 10 V (Note 4)		25.3		nC
Q_{gs}	Gate-to-Source Gate Charge			5.3		nC
Q_{gd}	Gate-to-Drain "Miller" Charge			8.3		nC
ESR	Equivalent Series Resistance	f = 1 MHz		4		Ω
SWITCHING CI	HARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 400 V, I _D = 6.5 A, V _{GS} = 10 V,		21.2		ns
t _r	Turn-On Rise Time	$R_g = 25 \Omega$ (Note 4)		18.5		ns
t _{d(off)}	Turn-Off Delay Time			110		ns
t _f	Turn-Off Fall Time	1		17.7		ns
SOURCE-DRA	IN DIODE CHARACTERISTICS					
I _S	Maximum Continuous Source-to-Drain Diode Forward Current				13	Α
I _{SM}	Maximum Pulsed Source-to-Drain Diode Forward Current				32.5	Α
V _{SD}	Source-to-Drain Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 6.5 A			1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 3.25 A,		370		ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100 A/μs		3.0		μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

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^{4.} Essentially independent of operating temperature typical characteristics.

TYPICAL CHARACTERISTICS

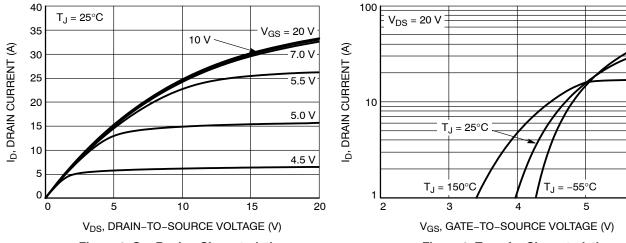


Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics

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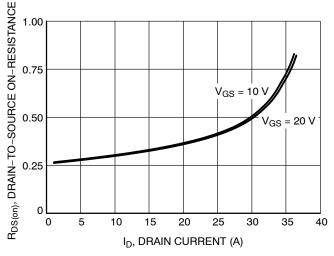


Figure 3. On Resistance vs. Drain Current

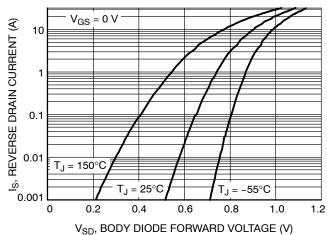


Figure 4. Diode Forward Voltage vs. Current

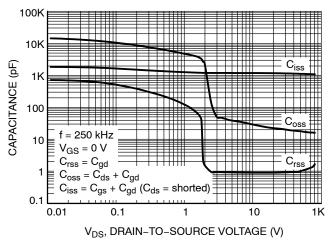


Figure 5. Capacitance Characteristics

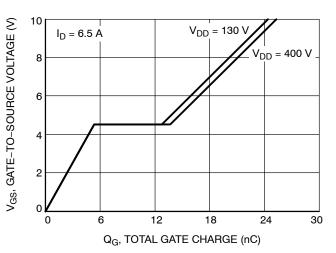


Figure 6. Gate Charge Characteristics

TYPICAL CHARACTERISTICS

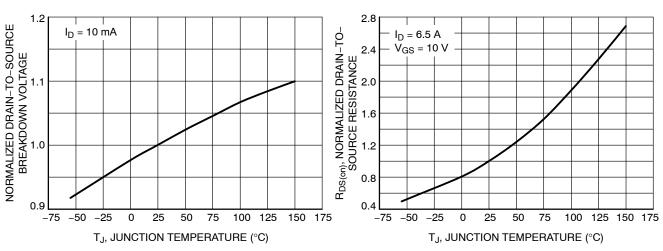


Figure 7. Normalized BV_{DSS} vs. Temperature

Figure 8. On-Resistance Variation vs. **Temperature**

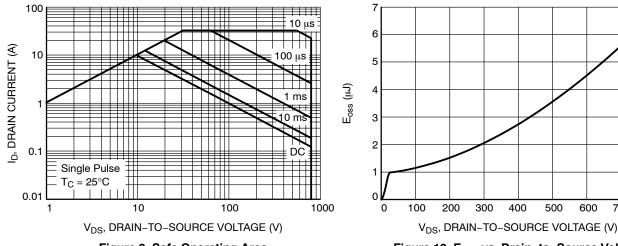


Figure 9. Safe Operating Area

Figure 10. E_{oss} vs. Drain-to-Source Voltage

500

600

700

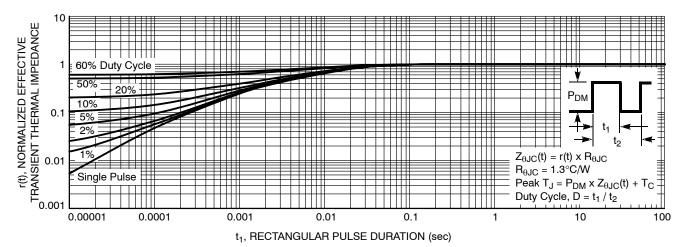


Figure 11. Transient Thermal Impedance

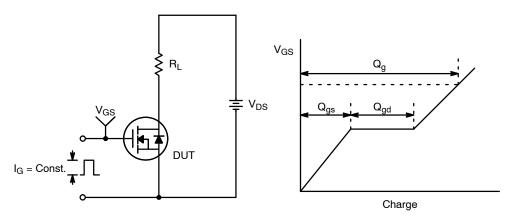


Figure 12. Gate Charge Test Circuit & Waveform

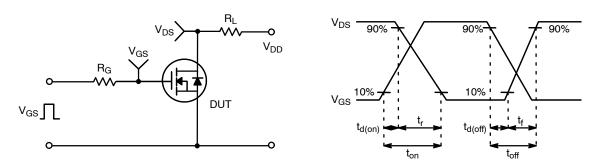


Figure 13. Resistive Switching Test Circuit & Waveforms

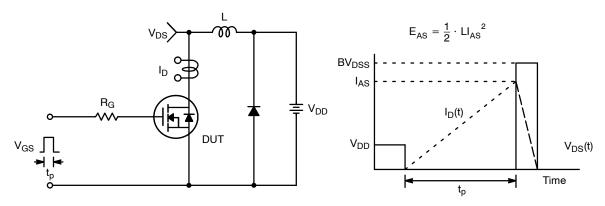


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

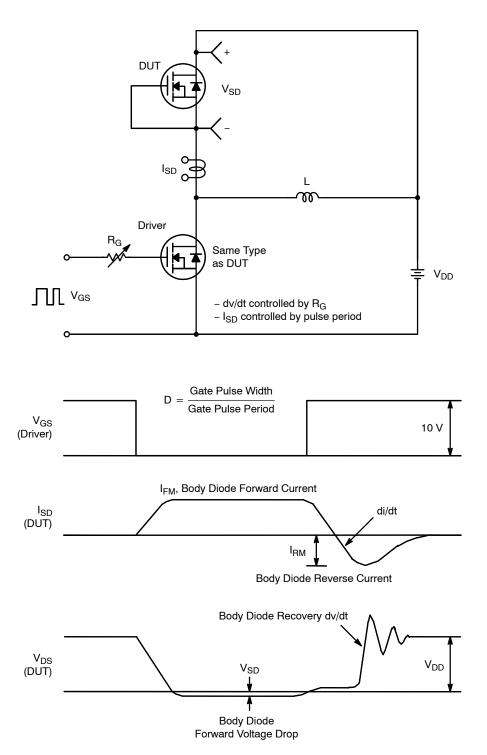
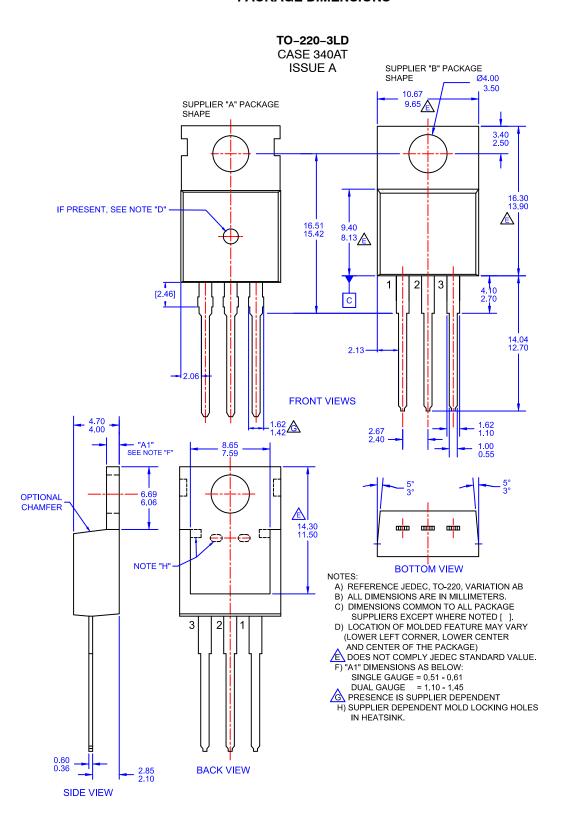


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

PACKAGE DIMENSIONS



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